## **Declaration For Patent Application**

As a below named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled\_. STRUCTURE OF THE STEM OF LED CHIP UNIT BULB (check one) is attached hereto. was files on Application Serial No. \_\_\_ and was amended on\_\_ (if applicable) I hereby state that I have reviewed and understand the contents of the above identified speciation, including the claim(s), as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a). I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: Prior Foreign Application(s) Priority Claimed ☐ Yes ☐ No (Number) (Day/Month/Year Filed) (Country) ☐ Yes ☐ No (Number) (Country) (Day/Month/Year Filed) I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 122, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: (Application Serial No.) (Filing Date) (Status) (patented, pending, abandoned) (Application Serial No.) (Filing Date) (Status) (patented, pending, abandoned) And I hereby appoint as principal attorneys Please direct all communications to the following address: I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. Full name of sole or first inventor \_\_\_\_\_ Date \_\_\_\_\_UN 06 2003 HSIN CHU CITY, TAIWAN P. O. BOX 7-288, TAIPEI 106, TAIWAN Post Office Address Full name of sole or Second inventor if any Inventor's signature Residence Citizenship \_\_

(Supply similar information and signature for third and subsequent joint inventors.)

Post Office Address \_\_

Attorne	y's	
Docket 1	No.	

## **VERIFIED STATEMENT OF SMALL ENTITY STATUS**

Honorable Commissioner of patent and Trademarks Washington, D. C. 20231

Sir:					
I hereby de	eclare that I am 🂢 th	e sole inventor 🔲 a	joint inventor of the invention		
entitled:	ntitled: STRUCTURE OF THE STEM OF LED CHIP UNIT BULB				
the invention being desc	ribed and claimed	in the specification	filed herewith, [] in the		
specification of applicat	ion Serial No	, filed	20		
and that I have not assig	ned, granted, conveye	d, or licensed, and t	hat I am under no obligation		
under contract or law to	assign, grant, convey	or license, any rights	s in the invention to any person		
who could not likewise	be classified as an ind	ependent inventor if	that person had made the		
invention, or to any cone	ern which would not	qualify as a small bu	siness concern or a nonprofit		
organization.					
I further de	eclare that all statemen	nts made herein of m	y own knowledge are true and		
that all statements made	on information and b	elief are believed to	be true; and further that these		
statements were made w	rith the knowledge tha	t willful false statem	ents and the like so made are		
punishable by fine or im	prisonment, or both, a	ınder Section 1001 o	f Title 18 of the United States		
Code, and that such will	ful false statements m	ay jeopardize the val	lidity of the application or any		
patent issuing thereon.					
Lee, Han-Ming					
NAME OF INVENTOR	NAME OF I	NVENTOR	NAME OF INVENTOR		
LZZ Hom 7 Signature of Inventor	minh.				
Signature of Inventor	Signature	of Inventor	Signature of Inventor		
JUN 06 2003					
Date	Date		Date		